

ABSTRACT

To provide a mold release film which, even if its thickness is thin, is unlikely to have wrinkles or pinholes formed when brought in close contact with a cavity surface of a mold, a mold release film capable of forming a resin-encapsulation portion which is less susceptible to cracking or chipping in a singulation step and which is excellent in adhesion to an ink layer, and a process for producing a semiconductor package using the mold release film.

A mold release film to be disposed on a cavity surface of a mold in a method for producing a semiconductor package wherein a semiconductor element is disposed in the mold and encapsulated with a curable resin to form a resin-encapsulation portion, characterized in that it has a first surface to be in contact with the curable resin at the time of forming the resin-encapsulation portion, and a second surface to be in contact with the cavity surface, at least one of the first surface and the second surface has irregularities formed thereon, and the surface having irregularities formed thereon, has an arithmetic mean roughness (Ra) of from 1.3 to 2.5 μm and a peak count (RPc) of from 80 to 200.